

U.S. Patent Application Serial No. 10/668,964
Amendment filed April 13, 2005
Reply to OA dated December 15, 2004

AMENDMENTS TO THE CLAIMS:

Please amend claims 1-3 as follows. This listing of claims will replace all prior versions, and listings, of claims in the application:

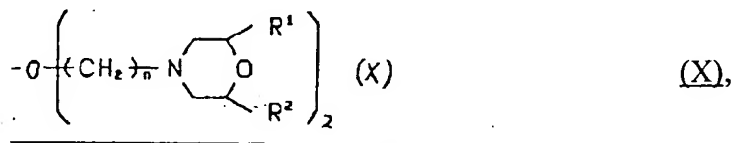
Listing of Claims:

Claim 1 (Currently amended): A solvent-free moisture-curable hot melt urethane resin composition comprising:

an isocyanate group-containing hot melt urethane prepolymer (A) prepared by reacting a polyisocyanate with a polyester polyol which comprises a condensate of a polyhydric alcohol and a polybasic acid,

wherein the polybasic acid is selected from the group consisting of a phthalic acid, an isophthalic acid, a terephthalic acid, and a mixture thereof;

a morpholine ether-based crosslinking catalyst (B) of general formula (X):



wherein R¹ and R² represent a hydrogen or an alkyl group and n represents a positive integer;

and

at least one sulfur atom-containing organic acid (C) selected from the group consisting of sulfonic acids and sulfinic acids ~~as essential components.~~

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Claim 2 (Currently amended): The solvent-free moisture-curable hot melt urethane resin composition according to claim 1, wherein the isocyanate group-containing hot melt urethane prepolymer (A) is a urethane prepolymer having an isocyanate group, originated from ~~diphenylmetane~~ diphenylmethane diisocyanates, at a molecular end of the urethane prepolymer.

Claim 3 (Currently amended): The solvent-free moisture-curable hot melt urethane resin composition according to claim 1, wherein the ~~morpholine-ether-based~~ crosslinking catalyst (B) comprises 2,2'-dimorpholino diethyl ether and/or di(2,6-dimethylmorpholinoethyl)ether.

Claim 4 (Original): The solvent-free moisture-curable hot melt urethane resin composition according to claim 1, wherein the sulfur atom-containing organic acid (C) comprises methanesulfonic acid and/or ethanesulfonic acid.